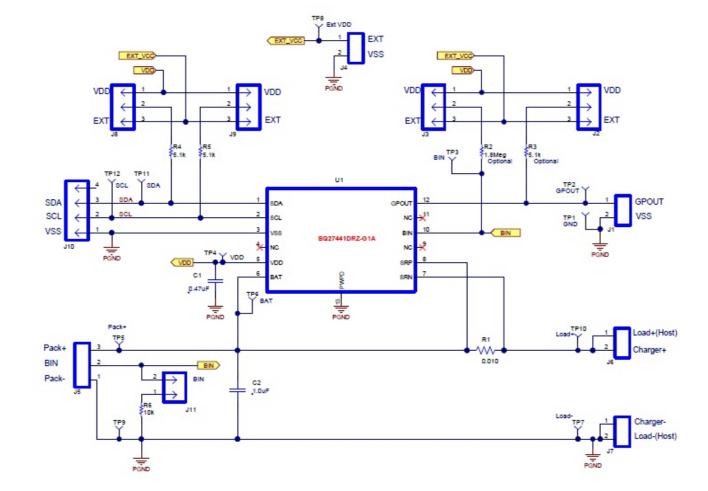
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			Number: PWR582	Rev: B	Sheet Title:	
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